IEC 62610-6

Edition 1.0 2020-03

INTERNATIONAL STANDARD

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Mechanical structures for electrical and electronic equipment – Thermal management for cabinets in accordance with IEC 60297 and IEC 60917 series – Part 6: Air recirculation and bypass of indoor cabinets



IEC 62610-6:2020-03 (en)

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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.240

ISBN 978-2-8322-8006-5

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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MECHANICAL STRUCTURES FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – THERMAL MANAGEMENT FOR CABINETS IN ACCORDANCE WITH IEC 60297 AND IEC 60917 SERIES –

Part 6: Air recirculation and bypass of indoor cabinets

FOREWORD

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International Standard IEC 62610-6 has been prepared by subcommittee 48D: Mechanical structures for electrical and electronic equipment, of IEC technical committee 48: Electrical connectors and mechanical structures for electrical and electronic equipment.

The text of this International Standard is based on the following documents:

CDV	Report on voting
48D/700/CDV	48D/715/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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A list of all parts in the IEC 62610 series, published under the general title *Mechanical structures for electrical and electronic equipment – Thermal management for cabinets in accordance with iec 60297 and iec 60917 series*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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INTRODUCTION

The signal speed and component density of electrical and electronic equipment in the ICT field and the FA field, such as high performance servers, communications equipment, and electronic control equipment have been steadily increasing. As a result, the heat generation density of the integrated circuits, the power consumption of the equipment, and therefore the cooling task has also been increasing. In a computer room common in the ICT field, where many cabinets for mounting subrack and/or chassis-based equipment are installed and high availability is required, it is necessary to pay attention so that the equipment does not experience high temperature problems.

To prevent high temperature problems with the electronic equipment, it is important that the air conditioning installed in a computer room effectively contributes to the cooling of the cabinet for mounting subrack and/or chassis-based equipment. Indicators relating to airflow such as recirculation and bypass, are used to judge the effectiveness of the air conditioning system. Recirculation is the ratio at which the cabinets in the computer room suck in their own exhaust air, which affects the thermal problems of the equipment as it raises the intake air temperature. Bypass is the ratio at which the cooled supply air does not pass through the cabinets in the computer room, and affects the energy efficiency as it increases the air conditioning energy. If these ratios, especially the recirculation ratio, are kept low, the airflow of the computer room can be regarded as effectively cooling the cabinets. Conversely, if air recirculation or bypass occurs, the temperature of subracks and/or chassis-based equipment in the cabinet rises. Therefore it is necessary to provide similar indices to measure the effectiveness of the cooling airflow for the equipment in the cabinet.

The existing standard for forced air cooling, IEC 62610-2, introduces a method for determining the ideal airflow for a forced air cooled cabinet assembled with associated subrack and/or chassis-based equipment. The standard also defines qualitative guidelines for avoiding recirculation in such cabinets and a server(computer) room. However, concrete numerical values and the evaluation method of the recirculation have not been defined. It was impossible to judge in advance whether the cabinet for mounting subrack and/or chassis-based equipment satisfies the environmental conditions, or whether the empty cabinet has sufficient cooling when subrack and/or chassis-based equipment are mounted.

This document defines a method for easily measuring the recirculation ratio (RC) and the bypass ratio (BP) of the airflow in a cabinet and provides performance levels of recirculation on effectiveness of the cooling airflow in such cabinets. This can be regarded as the degree of conformity with respect to behaviour of the airflow in the cabinet in the computer room. Alternatively, even for an outdoor cabinet including a heat exchanger and an air conditioner, this method can be effectively utilized as an index for knowing the degree of airflow appropriately contributing to cooling the internal space in which the equipment is mounted.

The purpose of this document is to provide:

- for the equipment integrator and development designer of the cabinet the criteria for efficiently and correctly determining the specification, and
- for the supplier of the cabinet the measuring and classifying method for the airflow recirculation rate of the subrack and/or chassis-based equipment installed in the cabinet.

This document is addressed to the mechanical structures in accordance with IEC 60297 and IEC 60917 series.

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MECHANICAL STRUCTURES FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – THERMAL MANAGEMENT FOR CABINETS IN ACCORDANCE WITH IEC 60297 AND IEC 60917 SERIES –

Part 6: Air recirculation and bypass of indoor cabinets

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1 Scope

This part of IEC 62610 which deals with thermal management for cabinets in accordance with IEC 60297 and IEC 60917 series, provides compatible measurement methods of recirculation ratio and bypass ratio which are indicators for defining quality of airflow in the forced air cooling that can be commonly applied to indoor cabinets for mounting subrack and/or chassis-based equipment.

NOTE 1 Both recirculation and bypass represent leakage airflows, i.e. detrimental phenomena in terms of cooling efficiency; their measurement is obviously aimed at their mitigation.

This document contains the following:

a) the definition of recirculation and bypass flow rates in the cooling of the cabinet,

b) the levels of the recirculation ratio RC,

c) the definition of the formula for the recirculation ratio RC_s of forced air cooling subrack and/or chassis-based equipment installed in the cabinet,

d) the definition formula of recirculation ratio RC_r and bypass rate BP_r of the entire cabinet,

e) the requirements of the measuring method of each temperature necessary for calculating the recirculation ratio RC_s, RC_r and bypass ratio BP_r.

NOTE 2 This document includes the definition of measuring bypass ratio, but excludes the definition of levels of bypass ratio.

The drawings used are not intended to indicate product design. They are only for explanatory indications for defining forced air cooling airflows.

The recirculation and bypass measurement methods dealt with in this document are assumed to be applied to a cabinet installed indoors. The cooling air inlet is at the front or the bottom of the cabinet and the heated air is exhausted to the rear or the top. These methods are also applicable to a cabinet that is installed outdoors and has a cooling device such as a heat exchanger or an air conditioner on the front or the back (see Annex C).

The recirculation ratio of a subrack or a cabinet is defined for each individual subrack or chassis-based equipment mounted in the cabinet or for the entire cabinet. The bypass ratio of a cabinet is defined for the entire cabinet.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60297-3-100, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-100: Basic dimensions of front panels, subracks, chassis, racks and cabinets*

IEC 60917-1, *Modular order for the development of mechanical structures for electrical and electronic equipment practices – Part 1: Generic standard*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.1
recirculation flow rate
f_{RC}
flow rate of the air that returns directly from the exhaust of the equipment to be cooled to the intake side of the equipment

3.2
bypass flow rate
f_{BP}
flow rate of the air going through a cabinet without going through any of the equipment to be cooled

3.3
recirculation ratio of a subrack
RC_s
ratio of the recirculation flow rate of a subrack or a chassis-based equipment to the flow rate of the equipment

3.4
recirculation ratio of a cabinet
RC_r
ratio of the total recirculation flow rate of all of the subracks mounted in a cabinet to the total flow rate of all of the subracks mounted in a cabinet

3.5
bypass ratio of a cabinet
BP_r
ratio of the bypass flow rate of a cabinet to the airflow rate of a cabinet

3.6
dummy thermal load
DTL
simulator that reproduces thermal fluid behaviour such as heat dissipation and flow rate generated by subrack and/or chassis-based equipment

Note 1 to entry: Generally, a heater and a fan mounted in a chassis are used, and the amount of heat dissipation and the fan flow rate can be adjusted.

4 Recirculation level

The recirculation level RL indicates the degree of recirculation of a subrack or a chassis or a cabinet and is represented by levels RL1 through RL4 according to the recirculation ratio of a subrack RC_s or recirculation ratio of a cabinet RC_r. See Table 1.

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